

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	27	"ein-eli".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/11/13 10:12
S2	13	starosvetsky.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/11/13 10:12
S3	40	abelev.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/11/13 10:13
S4	366	rabkin.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/11/13 10:13
S5	433	S1 S2 S3 S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/11/13 10:13
S6	2	S5 and (copper near5 cmp near5 slurry).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/11/13 10:13
S7	3	("6447371").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2008/11/13 11:06
S8	0	S7 and cation and anion	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/11/13 11:06
S9	2	S7 and "pH"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/11/13 11:06
S10	30	"6447371"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 13:23
S11	3	("6447371").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2008/12/01 13:23

S12	647	106/403.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 15:53
S13	0	156/659.1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 15:53
S14	0	106/290.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 15:53
S15	0	106/308.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 15:54
S16	537	106/404.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 15:54
S17	442	106/31.9.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 15:54
S18	647	106/403.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 15:54
S19	1168	523/200.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 15:54
S20	2539	S12 S13 S14 S15 S16 S17 S18 S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 15:54
S21	41	S20 and milling near2 (fluid or composition or mixture)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 15:54
S22	3	S21 and corrosion near inhibitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 16:33
S23	2	("20020047058").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2008/12/01 16:34
S24	2	S23 and pigment	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 16:34

S25	0	S23 and corrosion	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 16:39
S26	43330	corrosion adj inhibitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 16:40
S27	22004	corrosion adj inhibitor with (component or compound or material or composition)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 16:40
S28	1579	corrosion adj inhibitor with (component or compound or material or composition) and "106". clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/12/01 16:40
S29	7195	calomel near3 electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 10:42
S30	473	calomel near3 electrode with oxidation near potential	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 10:43
S31	41	calomel near3 electrode with oxidation near potential and oxidiz\$4 with (surface or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 10:43
S32	7	calomel near3 electrode with oxidation near potential same copper same (substrate or surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:16
S33	320	148/269.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:20
S34	1340	451/36.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:20
S35	4763	451/41.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:20
S36	3223	438/692.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:20

S37	1098	106/3.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:21
S38	34457	S33 S34 S35 S36 S37 "L12" "L13" "L14" "L15" "L16" "L17" "L18" "L19"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:21
S39	34457	S33 S34 S35 S36 S37 "L12" "L13" "L14" "L15" "L16" "L17" "L18" "L19"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:21
S40	653	106/403.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:22
S41	0	156/659.1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:22
S42	0	106/290.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:22
S43	0	106/308.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:22
S44	542	106/404.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:22
S45	452	106/31.9.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:22
S46	653	106/403.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:22
S47	1182	523/200.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:22
S48	12571	S33 S34 S35 S36 S37 S40 S41 S42 S43 S44 S45 S46 S47	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:22
S49	198	S48 and ("KMnO.sub.4" or "KMnO4" or (potassium near permanganate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:23

S50	157	S48 and ("KMnO.sub.4" or "KMnO4" or (potassium near permanganate)) same (oxidizing or oxidizer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:24
S51	8	S48 and ("KMnO.sub.4" or "KMnO4" or (potassium near permanganate)) same (oxidizing or oxidizer) with (known or conventional or general or widely or usually)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:24
S52	6	((("5800577") or ("5840629") or ("6313039")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2009/03/16 11:40
S53	2	S52 and (carbonate or "CsCO3" or "CsCO.sub.3")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 11:41
S54	300	"pH" near4 (adjusting or adjusted or adjuster) same cesium same carbonate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:01
S55	2	"pH" near4 (adjusting or adjusted or adjuster) same cesium same carbonate and polishing. ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:01
S56	229	"pH" near4 (adjusting or adjusted or adjuster) same cesium adj carbonate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:02
S57	0	"pH" near4 (adjusting or adjusted or adjuster) same cesium adj carbonate and (polishing or planarizing or planarization or abrading or CMP).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:02
S58	7	"pH" near4 (adjusting or adjusted or adjuster) same cesium adj carbonate same (known or conventional or usually or generally or widely)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:02

S59	68	("20020066234" "20040144755" "20040226918" "20050252092" "4632727" "4671851" "4789648" "4910155" "4944836" "4954142" "4956313" "5137544" "5157876" "5209816" "5225034" "5245790" "5340370" "5354490" "5476606" "5527423" "5575837" "5676587" "5770095" "5800577" "5840629" "6126514" "6126853" "6313039" "6383240" "6432828" "6447371" "6569350" "6676484" "6831015"). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:06
S60	0	S59 and (cesium adj carbonate) with "pH" near4 (adjuster or adjusting or adjusted)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:07
S61	0	S59 and (cesium adj carbonate) same "pH" near4 (adjuster or adjusting or adjusted)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:07
S62	0	S59 and (cesium adj carbonate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:07
S63	0	S59 and ("CsCO.sub.3" or "CsCO3")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:08
S64	3	S59 and "pH" with adjust \$4 with alkali	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:08
S65	15586	("CsCO.sub.3" or "CsCO3" or (cesium adj carbonate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:10
S66	42	("CsCO.sub.3" or "CsCO3" or (cesium adj carbonate)) with "pH" near4 adjust\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:10
S67	17124	"pH" near4 adjust\$4 with alkali	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:12

S68	351	"pH" near4 adjust\$4 with alkali and (polishing or CMP or planarizing or planarization or abrading or abrasive).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:13
S69	0	"pH" near4 adjust\$4 with alkali and (polishing or CMP or planarizing or planarization or abrading or abrasive).ab. and ((cesium adj carbonate) or "CsCO.sub.3" or "CsCO3")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:13
S70	0	"pH" near4 adjust\$4 with alkali and (polishing or CMP or planarizing or planarization or abrading or abrasive).ab. and ((cesium near carbonate) or "CsCO.sub.3" or "CsCO3")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:13
S71	0	"pH" near4 adjust\$4 with alkali and (polishing or CMP or planarizing or planarization or abrading or abrasive).ab. and ((cesium near 5carbonate) or "CsCO.sub.3" or "CsCO3")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:13
S72	3	"pH" near4 adjust\$4 with alkali and (polishing or CMP or planarizing or planarization or abrading or abrasive).ab. and ((cesium near5 carbonate) or "CsCO.sub.3" or "CsCO3")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 12:13
S73	2	("6589099").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2009/03/16 13:59
S74	4	((("6589099") or ("5897375")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2009/03/16 15:13
S75	0	S74 and ((potassium adj carbonate) or (cesium adj carbonate) or "CsCO.sub.3" or "CsCO3")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:14
S76	0	S74 and carbonate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:14

S77	139	potassium adj carbonate with known with "pH"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:19
S78	0	known near3 base with potassium adj carbonate with "pH" and polishing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:22
S79	0	known near3 base with potassium adj carbonate with "pH" and (planarizing or CMP or polishing or planarization or abrading or lapping)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:22
S80	0	known near3 base with ("K ₂ CO ₃ " or "K.sub.2 CO.sub.3" or "K.sub.2CO.sub.3") with "pH" and (planarizing or CMP or polishing or planarization or abrading or lapping)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:23
S81	0	known near3 base with ("K ₂ CO ₃ " or "K.sub.2 CO.sub.3" or "K.sub.2CO.sub.3") with "pH"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:23
S82	52	("K ₂ CO ₃ " or "K.sub.2 CO.sub.3" or "K.sub.2CO.sub.3") with "pH" and (planarizing or CMP or polishing or planarization or abrading or lapping)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:24
S83	22	("K ₂ CO ₃ " or "K.sub.2 CO.sub.3" or "K.sub.2CO.sub.3") with "pH" and (planarizing or CMP or polishing or planarization or abrading or lapping) and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:24
S84	11	("K ₂ CO ₃ " or "K.sub.2 CO.sub.3" or "K.sub.2CO.sub.3") with "pH" and (planarizing or CMP or polishing or planarization or abrading or lapping) same copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:25
S85	191	((cesium near carbonate) or "CsCO ₃ " or "CsCO.sub.3") with "pH"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:39
S86	46	((cesium near carbonate) or "CsCO ₃ " or "CsCO.sub.3") with "pH" near5 adjust\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:39

S87	3	("6447371").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2009/03/16 15:49
S88	1	S87 and ammonium	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 15:51
S89	3448	51/294-297.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 16:07
S90	0	S89 and cesium near carbonate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 16:07
S91	16	S89 and potassium near carbonate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 16:07
S92	28	ein-eli.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 16:09
S93	14	starosvetsky.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 16:09
S94	0	"abelev.in"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 16:09
S95	40	abelev.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 16:09
S96	368	rabkin.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 16:09
S97	436	S92 S93 S95 S96	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 16:09
S98	1	S97 and (oxidation near potential).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 16:09
S99	3	S97 and passiv\$6.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/03/16 16:10

S100	660	106/403.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:54
S101	0	156/659.1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:54
S102	0	106/290.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:54
S103	0	106/308.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:54
S104	546	106/404.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:54
S105	464	106/31.9.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:54
S106	660	106/403.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:54
S107	1203	523/200.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:54
S108	2604	S100 S101 S102 S103 S104 S105 S106 S107	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:54
S109	0	S108 and (polishing or planarizing or planarization or lapping or abrading or CMP or passivat\$5).ab. and (copper near10 (substrate or surface)) and (abrasive same (silica or "SiO2" or "SiO.sub.2")) and (oxidizer or oxidizing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:55

S110	1119	(polishing or planarizing or planarization or lapping or abrading or CMP or passivat\$5).ab. and (copper near10 (substrate or surface)) and (abrasive same (silica or "SiO2" or "SiO.sub.2")) and (oxidizer or oxidizing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:55
S111	916	(polishing or planarizing or planarization or lapping or abrading or CMP or passivat\$5).ab. and (copper near10 (substrate or surface)) and (abrasive same (silica or "SiO2" or "SiO.sub.2")) and (oxidizer or oxidizing) and (acerate or adipate or bicarbonate or bisulfate or carbonate or chloroacetate or citrate or crotonate or cyanate or glytarate or dihydrogen near phosphate or bydrogen near phosphate or hydrogen near sulfate or hydroxide or lactae or malate or mandelate or malonate or oxalate or permanganate or phosphate or hydrogen near phthalate or phthalate or propanoate or succinate or sulfanilate or sulfate or tartarate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:57
S112	73	(polishing or planarizing or planarization or lapping or abrading or CMP or passivat\$5).ab. and (copper near10 (substrate or surface)) and (abrasive same (silica or "SiO2" or "SiO.sub.2")) and (oxidizer or oxidizing) and (acerate or adipate or bicarbonate or bisulfate or carbonate or chloroacetate or citrate or crotonate or cyanate or glytarate or dihydrogen near phosphate or bydrogen near phosphate or hydrogen near sulfate or hydroxide or lactae or malate or mandelate or	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2009/10/27 09:58

		malonate or oxalate or permanganate or phosphate or hydrogen near phthalate or phthalate or propanoate or succinate or sulfanilate or sulfate or tartarate) not (complexing near agent or film near forming or "film-forming" or ammonium)				
S113	2	("20030212283").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2009/10/27 15:00
S114	1515	((cmp or abrasive or polishing or planarizing or planarization or lapping or abrading) same copper).ab. and pH	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/04/30 15:21
S115	655	((cmp or abrasive or polishing or planarizing or planarization or lapping or abrading) same copper).ab. and pH and (acetate or adipate or bicarbonate or bisulfate or carbonate or chloroacetate or bydrogen near sulfate or hyroxide or lactate or malate or maleate or mandelate or malonate or oxalate or permanganate or phosphate or hydrogen near phthalate or phthalate or propanoate or succinate or sulfanilate or sulfate or tartarate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/04/30 15:25
S116	545	((cmp or abrasive or polishing or planarizing or planarization or lapping or abrading) same copper).ab. and pH and (acetate or adipate or bicarbonate or bisulfate or carbonate or chloroacetate or bydrogen near sulfate or hyroxide or lactate or malate or maleate or mandelate or malonate or oxalate or permanganate or phosphate or hydrogen near phthalate or phthalate or propanoate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/04/30 15:36

		or succinate or sulfanilate or sulfate or tartarate) same2 (sodium or potassium ro lithium or robidium or beryllium or magnesium or calcium or strontium or barium or cesium or "Li" or "Na" or "K" or "Rb" or "Cs" or "Be" or "Mg" or "Ca" or "Sr" or "Ba")				
S117	466	((cmp or abrasive or polishing or planarizing or planarization or lapping or abrading) same copper).ab. and pH and (acetate or adipate or bicarbonate or bisulfate or carbonate or chloroacetate or bydrogen near sulfate or hyroxide or lactate or malate or maleate or mandelate or malonate or oxalate or permanganate or phosphate or hydrogen near phthalate or phthalate or propanoate or succinate or sulfanilate or sulfate or tartarate) same (sodium or potassium ro lithium or robidium or beryllium or magnesium or calcium or strontium or barium or cesium or "Li" or "Na" or "K" or "Rb" or "Cs" or "Be" or "Mg" or "Ca" or "Sr" or "Ba")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/04/30 15:37
S118	60	((cmp or abrasive or polishing or planarizing or planarization or lapping or abrading) same copper).ab. and pH and (acetate or adipate or bicarbonate or bisulfate or carbonate or chloroacetate or bydrogen near sulfate or hyroxide or lactate or malate or maleate or mandelate or malonate or oxalate or permanganate or phosphate or hydrogen near phthalate or phthalate or propanoate or succinate or sulfanilate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/04/30 15:37

		or sulfate or tartarate) same (sodium or potassium or lithium or rubidium or beryllium or magnesium or calcium or strontium or barium or cesium or "Li" or "Na" or "K" or "Rb" or "Cs" or "Be" or "Mg" or "Ca" or "Sr" or "Ba") not (ammonium or corrosion near inhibitor or "film- forming" or film near forming or complexing)				
S119	208009	(cmp or abrasive or polishing or planarizing or planarization or lapping or abrading).ab. not ("film-forming" or film near forming or corrosion near inhibitor or complexing or ammonium)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/04/30 15:50
S120	25309	((cmp or abrasive or polishing or planarizing or planarization or lapping or abrading) near2 (slurry or material or composition)).ab. not ("film-forming" or film near forming or corrosion near inhibitor or complexing or ammonium)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/04/30 15:51
S121	576	pH with ("9" or "10" or "11" or "12" or "13") and (CMP or abrasive or planarizing or planarization or abrading or lapping or polishing).ti. and copper.ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/04/30 15:52
S122	100	pH with ("9" or "10" or "11" or "12" or "13") and (CMP or abrasive or planarizing or planarization or abrading or lapping or polishing).ti. and copper.ab. not (complexing or corrosion near inhibitor or "film- forming" or film near forming or ammonium)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/04/30 15:53

S123	87	pH near5 ("9" or "10" or "11" or "12" or "13") and (CMP or abrasive or planarizing or planarization or abrading or lapping or polishing).ti. and copper.ab. not (complexing or corrosion near inhibitor or "film-forming" or film near forming or ammonium)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/04/30 15:53
S124	42	pH near5 ("9" or "10" or "11" or "12" or "13") and ((CMP or abrasive or planarizing or planarization or abrading or lapping or polishing) near5 (slurry or material or composition)).ti. and copper.ab. not (complexing or corrosion near inhibitor or "film-forming" or film near forming or ammonium)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/04/30 15:53
S125	13	pH near5 ("9" or "10" or "11" or "12" or "13") and ((CMP or abrasive or planarizing or planarization or abrading or lapping or polishing) near5 (slurry or material or composition)).ti. and copper.ab. not (complexing or corrosion near inhibitor or "film-forming" or film near forming or ammonium) and (oxidizer or oxidizing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/04/30 15:54
S126	934	(polishing or planarizing or abarding or planarization or lapping) and permanganate and (carbonate or bicarbonate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 10:04
S127	237	(polishing or planarizing or abarding or planarization or lapping).ab. and permanganate and (carbonate or bicarbonate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 10:04

S128	5	(polishing or planarizing or abarding or planarization or lapping). ab. and (permanganate and (carbonate or bicarbonate)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 10:05
S129	2	("20030153188").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2010/05/07 10:05
S130	1	S129 and permanganate and carbonate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 10:25
S131	129	(polishing or planarizing or abarding or planarization or lapping). ab. and (potassium near permanganate or "KMnO ₄ " or "KMnO ₄ ") and (carbonate or bicarbonate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 10:57
S132	23	(polishing or planarizing or abarding or planarization or lapping). ab. and (potassium near permanganate or "KMnO ₄ " or "KMnO ₄ ") and (carbonate or bicarbonate) and (film near forming or "film-forming" or corrosion near inhibit\$3) and complexing and ammonium	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 10:58
S133	2	(polishing or planarizing or abarding or planarization or lapping). ab. and (potassium near permanganate or "KMnO ₄ " or "KMnO ₄ ") and (carbonate or bicarbonate) and (film near forming or "film-forming" or corrosion near inhibit\$3) and copper near complexing and ammonium	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 10:58
S134	106	S131 not S132	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 10:58

S135	2	("5800577").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2010/05/07 11:20
S136	1	S135 and abrasive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 11:20
S137	18	S131 not S132 not (ammonia or amine)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 11:22
S138	20	S131 not S132 not (ammonia or ammonium)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 11:24
S139	121	(polishing or planarizing or abarding or planarization or lapping). ab. and (potassium near permanganate or "KMnO. sub.4" or "KMnO4") and (carbonate or bicarbonate) and "pH"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 11:25
S140	99	S139 not S132	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 11:26
S141	9	(cesium adj carbonate or "CsCO.sub.3" or "CsCO3") and (polishing or planarizing or planarization or lapping or abrading).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 11:58
S142	2	("20030153188").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2010/05/07 13:27
S143	1	S142 and ("film-forming" or film near forming or corrosion near inhibit\$4 or complexing or ammonia or ammonium or amine)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 13:28
S144	2	("20010051433").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2010/05/07 13:46
S145	1	S144 and (oxidizing or oxidizer or permanganate or peroxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 13:46

S146	9	(potassium adj permanganate or "KMnO4" or "KMnO. sub.4") same2 (oxidizing or oxidizer) with known and (polishing or planarizing or planarization or lapping or abrading).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 14:06
S147	322	148/269.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S148	1413	451/36.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S149	4964	451/41.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S150	3434	438/692.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S151	1131	106/3.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S152	669	106/403.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S153	0	156/659.1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S154	0	106/290.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S155	0	106/308.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S156	553	106/404.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15

S157	478	106/31.9.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S158	669	106/403.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S159	1232	523/200.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S160	4	(S147 S148 S149 S150 S151 S152 S153 S154 S155 S156 S157 S158 S159) and (polishing or planarizing or planarization or lapping or abrading).ab. and pH and carbonate and permanganate not ("film- forming" or (film near forming) or complexing or ammonium or ammonia)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:15
S161	428	(starosvetsky.in. or abelev.in. or rabkin.in.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:16
S162	28	ein-eli.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:16
S163	1	(S161 S162) and (pH and copper and oxidation). clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/05/07 16:16
S164	2964	51/307.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 10:28
S165	692	106/403.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26
S166	0	156/659.1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26
S167	0	106/290.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26

S168	0	106/308.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26
S169	570	106/404.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26
S170	502	106/31.9.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26
S171	692	106/403.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26
S172	1275	523/200.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26
S173	1467	451/36.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26
S174	5100	451/41.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26
S175	3571	438/692.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26
S176	1146	106/3.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26
S177	3149	(S165 S166 S167 S168 S169 S170 S171 S172 S173 S174 S175 S176 S164) and (copper or "CuO" or "CuO2" or "CuO. sub.2") same (substrate or surface or wire)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26

S178	892	(S165 S166 S167 S168 S169 S170 S171 S172 S173 S174 S175 S176 S164) and (copper or "CuO" or "CuO2" or "CuO. sub.2") same (substrate or surface or wire) and (solution or slurry or composition).ab. not (complexing near agent or ammonium near cation or film near forming near agent)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 11:26
S179	1	(starosvetsky.in. or abelev.in. or rabkin.in.) and (copper and composition and passivating).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 16:25
S180	1	(starosvetsky.in. or abelev.in. or rabkin.in.) and (copper and composition and cation). clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 16:25
S181	0	(starosvetsky.in. or abelev.in. or rabkin.in.) and (cation and (oxidizing or oxidizer) and potential). clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 16:27
S182	1	(starosvetsky.in. or abelev.in. or rabkin.in.) and (cation and (oxidizing or oxidizer) and potential). clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 16:27
S183	3586	51/294-297.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 16:34
S184	3	S183 and ((oxidizing or oxidizer) and copper and abrasive).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 16:35
S185	2	S183 and ((oxidizing or oxidizer) same copper same abrasive same (composition or slurry or solution))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 16:35
S186	0	S183 and ((oxidizing or oxidizer) same copper same abrasive same (composition or slurry or solution)) and pH	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 16:36

S187	1146	106/3.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 16:54
S188	28	S187 and (copper with surface) and passivat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 16:55
S189	27	S187 and (copper with surface) and passivat\$4 and pH	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 16:55
S190	27	S187 and (copper with surface) and passivat\$4 and pH same (solution or slurry or composition)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2011/02/03 16:55

2/ 4/ 2011 8:45:39 AM

**C:\ Documents and Settings\ pparvini\ My Documents\ EAST\ Workspaces\ 10551714_copper CMP
slurry composition.wsp**